

Copper

SLOTOCOUP CU 50

SLOTOCOUP CU 50 is a process for copper plating of printed circuit boards (PCB) after direct metallization, for pre-plating or pattern plating after the copper process. It ensures good metal distribution, quick coverage down the holes and excellent throwing power.

The copper deposits are fine grained to moderate bright and ductile.

Since the concentrations of the additives in the electrolyte can be controlled by CVS (Cyclic Voltammetric Stripping), an optimal control of the process can be ensured. No detrimental breakdown products are formed even after extended periods of operation, so regular carbon treatments aren't necessary.

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.

Important:

Please read this instruction carefully prior to the use of the process and carefully follow all the parameters that have a direct influence on the operation. We reserve the right to make technical changes. In the interest of safety, please pay attention to the hazard warnings on the labels of the containers. The minimum shelf life of the products is included on the labels and is also available in the appropriate Quality Assurance (QA03).

The current IMDS number of the layer deposited from the process is available on the internet at www.schloetter.com/downloads.

For the storage of chemical products the TRGS 510 must be followed.

If the additives used in this process contain a SVHC-substance, then this will be specified in the corresponding Material Safety Data Sheet, section 15.

